

IN THE CLAIMS

Please cancel claims 1-15 and 19-21. Please amend claims 16-18 and add new claims 22-33. All currently pending claims and status indicators have been reproduced in their entirety below.

1-15. (Canceled)

16. (Currently Amended) A method for disposing an adhesive material onto an integrated circuit die comprising:

- (a) — fabricating a plurality of integrated circuit die on a wafer;
- (b) — testing the integrated circuit die on the wafer to determine electrically good integrated circuit die;
- (c) — producing a wafer map depicting the electrically good integrated circuit die; and
- (d) — disposing an adhesive material onto only the electrically good integrated circuit die in accordance with the wafer map.

17. (Currently Amended) The method, as set forth in claim 16, wherein disposing the adhesive act (d) comprises the act of disposing an adhesive tape onto the electrically good integrated circuit die in accordance with the wafer map.

18. (Currently Amended) The method, as set forth in claim 16, wherein disposing the adhesive ~~and~~ (d) comprises the act of disposing an adhesive paste onto the electrically good integrated circuit die in accordance with the wafer map.

19-21. (Canceled)

22. (New) The method, as set forth in claim 16, comprising forming an integrated circuit package comprising the electrically good integrated circuit die.

23. (New) The method, as set forth in claim 16, comprising forming a board on chip package comprising the electrically good integrated circuit die.

24. (New) The method, as set forth in claim 16, comprising forming a lead on chip package comprising the electrically good integrated circuit die.

25. (New) The method, as set forth in claim 16, wherein the acts are performed in the recited order.

26. (New) A method comprising:

identifying electrically good integrated circuit die on a wafer; and
disposing an adhesive material onto only the electrically good integrated circuit die on the wafer.

27. (New) The method, as set forth in claim 26, comprising producing a wafer map depicting the electrically good integrated circuit die.

28. (New) The method, as set forth in claim 26, wherein identifying comprises identifying the electrically good integrated circuit die using a wafer map.

29. (New) The method, as set forth in claim 26, wherein disposing the adhesive material comprises disposing an adhesive tape.

30. (New) The method, as set forth in claim 26, wherein disposing the adhesive material comprises disposing an adhesive paste.

31. (New) The method, as set forth in claim 26, comprising forming an integrated circuit package comprising the electrically good integrated circuit die.

32. (New) The method, as set forth in claim 26, comprising forming a board on chip package comprising the electrically good integrated circuit die.

33. (New) The method, as set forth in claim 26, comprising forming a lead on chip package comprising the electrically good integrated circuit die.

Conclusion

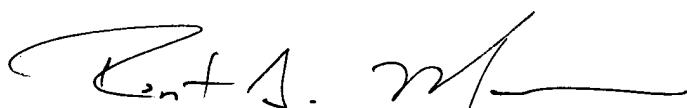
In view of the amendments set forth above, Applicant respectfully requests consideration of present claims 16-18 and 22-33. If the Examiner believes that a telephonic interview will help speed this application toward issuance, the Examiner is invited to contact the undersigned at the telephone number listed below.

General Authorization for Payment of Fees and Extensions of Time

In accordance with 37 C.F.R. § 1.136, Applicant hereby provides a general authorization to treat this and any future reply requiring an extension of time as incorporating a request therefor. Furthermore, Applicant authorizes the Commissioner to charge the appropriate fee for the additional claims and for any extension of time to Deposit Account No. 13-3092; Order No. MICS:0045--1/FLE (99-0663-1).

Respectfully submitted,

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